IPC ASSOCIATION CONN ELECTRONICS INDU	Material Comp © Copyright 2005. I international and Par	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					erials and N	ials and Mfg Information			
upplier Info	formation						·								
Company name	e*	Company unique ID			τ	Unique ID Authority				Respon	Response Date*				
nsemi										2024-0	2024-05-01				
Contact Name		Title - Contact			1	Phone - Contact*				Email	Email - Contact*				
Product-Env-S	Stewards		Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized Rep	presentative*	Title - Representative			1	Phone - Representative*				Email	Email - Representative*				
roduct-Env-S	Stewards	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com				
Req	Requester Item Number Mfr Item		m Number Mfr Item Name				Effective Dat	ive Date Version Manufacturing Sit		Manufacturing Site		Weight*	UOM	Unit Type	
		NVATS4	NVATS4A102PZT4G PCH 4.5V DRIVE SERIES		SERIES		2024-05-01			CNG		262.59	mg	Each	
Ianufacturi	ing Proccess Informa	tion													
Terminal Plating / Grid Array Material		•		-STD-020 MS	SL Rating	Peak Process Body Tempe		ly Temperati			ature Numb	per of Reflow Cyc	eles		
contains Bi			CU Alloy 1				260 C 30			seconds 3					
omments															
vel 1 - maxim	um time at peak temperatu	re during sol	dering is 10-3	0 seconds											
or more infort	mation regarding material	composition]	please refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU										
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale app										
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).										
Exemption List Version	EL-2011/534/EU									
Declaration Signature										
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.										
Supplier Digital Signature Ra	astislav Drska	-En								

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	1.66	mg	Supplier	Silicon (Si)	7440-21-3		1.66	mg
Die Attach	2.85		Supplier	Silver (Ag)	7440-22-4		0.057	mg
			A	Lead (Pb)	7439-92-1	7a	2.6505	mg
			Supplier	Tin (Sn)	7440-31-5		0.1425	mg
Lead Frame	148.04	"	Supplier	Tin (Sn)	7440-31-5		0.2221	mg
			Supplier	Copper (Cu)	7440-50-8		147.8179	mg
Mold Compound-Black	106.73			Phenolic Resin	proprietary data		2.6683	mg
			Supplier	Epoxy Phenol Resin	Proprietary Data		8.8052	mg
			Supplier	Carbon Black (C)	1333-86-4		0.5336	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		94.1892	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		0.5336	mg
Plating	3.31	mg	В	Bismuth (Bi)	7440-69-9		0.0199	mg
			Supplier	Tin (Sn)	7440-31-5		3.2901	mg